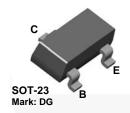


March 2014

# **BCW68G PNP General-Purpose Amplifier**

## **Description**

This device is designed for general-purpose amplifier and switching applications at currents to 500 mA. Sourced from process 63.



# **Ordering Information**

| Part Number | Marking | Package   | Packing Method |
|-------------|---------|-----------|----------------|
| BCW68G      | DG      | SOT-23 3L | Tape and Reel  |

# Absolute Maximum Ratings(1),(2)

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only. Values are at  $T_A = 25$ °C unless otherwise noted.

| Symbol                            | Parameter  | Value | Unit |
|-----------------------------------|--|-------|------|
| V <sub>CEO</sub>                  | Collector-Emitter Voltage                          | -45   | V    |
| V <sub>CBO</sub>                  | Collector-Base Voltage                             | -60   | V    |
| V <sub>EBO</sub>                  | Emitter-Base Voltage                               | -5    | V    |
| I <sub>C</sub>                    | Collector Current - Continuous                     | -800  | mA   |
| T <sub>J</sub> , T <sub>STG</sub> | Junction and Storage Temperature Range -55 to +150 |       | °C   |

#### Notes

- 1. These ratings are based on a maximum junction temperature of 150°C.
- These are steady-state limits. Fairchild Semiconductor should be consulted on applications involving pulsed or low-duty-cycle operations.

## Thermal Characteristics(3)

Values are at  $T_A = 25$ °C unless otherwise noted.

| Symbol          | Parameter                               | Max. | Unit  |
|-----------------|---|------|-------|
| В               | Total Device Dissipation                | 350  | mW    |
| P <sub>D</sub>  | Derate Above T <sub>A</sub> = 25°C      | 2.8  | mW/°C |
| $R_{\theta JA}$ | Thermal Resistance, Junction to Ambient | 357  | °C/W  |

### Note:

3. Device mounted on FR-4 PCB 40 mm X 40 mm X 1.5 mm.

## **Electrical Characteristics**

Values are at  $T_A = 25$ °C unless otherwise noted.

| Symbol                | Parameter                            | Conditions  | Min. | Max. | Unit |
|-----------------------|--------------------------------------|---|------|------|------|
| V <sub>(BR)CEO</sub>  | Collector-Emitter Breakdown Voltage  | $I_C = -10 \text{ mA}, I_B = 0$   | -45  |      | V    |
| V <sub>(BR)CES</sub>  | Collector-Emitter Breakdown Voltage  | I <sub>C</sub> = -10 μA   | -60  |      | V    |
| V <sub>(BR)CBO</sub>  | Collector-Base Breakdown Voltage     | $I_C = -100  \mu A, I_E = 0$  | -60  |      | V    |
| V <sub>(BR)EBO</sub>  | Emitter-Base Breakdown Voltage       | $I_E = -10  \mu A,  I_C = 0$  | -5.0 |      | V    |
| 1                     | Collector Cut-Off Current            | V <sub>CE</sub> = -45 V   |      | -20  | nA   |
| ICES                  |                                      | V <sub>CE</sub> = -45V, T <sub>A</sub> = 150°C  |      | -10  | μΑ   |
| I <sub>EBO</sub>      | Emitter Cut-Off Current              | V <sub>EB</sub> = -4.0 V  |      | -20  | nA   |
| h <sub>FE</sub>       | DC Current Gain                      | $I_C = -10 \text{ mA}, V_{CE} = -1.0 \text{ V}$   | 120  |      |      |
|                       |                                      | $I_C = -100 \text{ mA}, V_{CE} = -1.0 \text{ V}$  | 160  | 400  |      |
|                       |                                      | $I_C = -300 \text{ mA}, V_{CE} = -1.0 \text{ V}$  | 60   |      |      |
| V <sub>CE</sub> (sat) | Collector-Emitter Saturation Voltage | $I_C = -300 \text{ mA}, I_B = -30 \text{ mA}$   |      | -1.5 | V    |
| V <sub>BE</sub> (sat) | Base-Emitter Saturation Voltage      | $I_C = -500 \text{ mA}, I_B = -50 \text{ mA}$   |      | -2.0 | V    |
| f <sub>T</sub>        | Current Gain - Bandwidth Product     | I <sub>C</sub> = -20 mA, V <sub>CE</sub> = -10 V,<br>f = 100 MHz  | 100  |      | MHz  |
| C <sub>ob</sub>       | Output Capacitance                   | $V_{CB} = -10 \text{ V}, I_{E} = 0,$<br>f = 1.0 MHz   |      | 18   | pF   |
| C <sub>ib</sub>       | Input Capacitance                    | $V_{EB} = -0.5 \text{ V}, I_{C} = 0,$<br>f = 1.0 MHz  |      | 105  | pF   |
| NF                    | Noise Figure                         | $\begin{split} I_C &= \text{-}0.2 \text{ mA, V}_{CE} = \text{-}5.0 \text{ V,} \\ R_S &= 1.0 \text{ k}\Omega, \text{ f} = 1.0 \text{ kHz,} \\ B_W &= 200 \text{ Hz} \end{split}$ |      | 10   | dB   |

# **Typical Performance Characteristics**

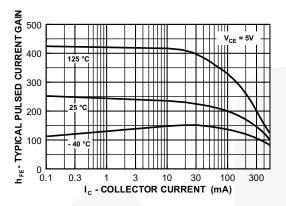


Figure 1. Typical Pulsed Current Gain vs. Collector Current

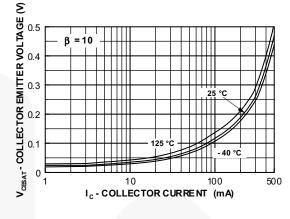


Figure 2. Collector-Emitter Saturation Voltage vs. Collector Current

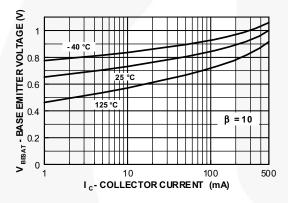


Figure 3. Base-Emitter Saturation Voltage vs. Collector Current

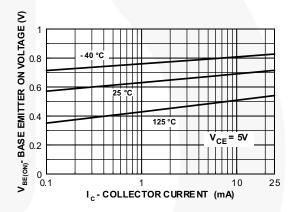


Figure 4. Base-Emitter On Voltage vs. Collector Current

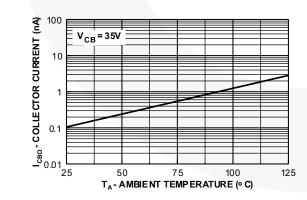


Figure 5. Collector Cut-Off Current vs.
Ambient Temperature

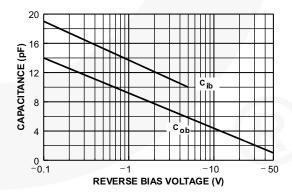


Figure 6. Input and Output Capacitance vs. Reverse Bias Voltage

# **Typical Performance Characteristics** (Continued)

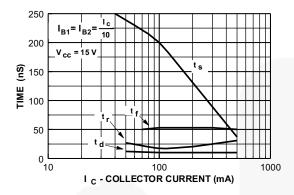


Figure 7. Switching Times vs. Collector Current

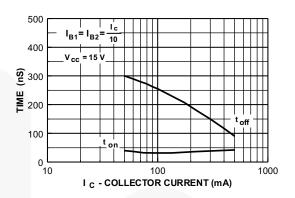


Figure 8. Turn-On and Turn-Off Times vs. Collector Current

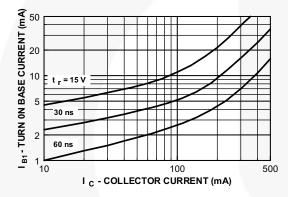


Figure 9. Rise Time vs. Turn-On Base Current

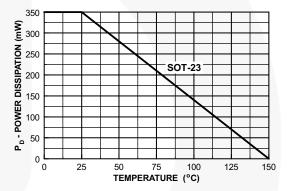


Figure 10. Power Dissipation vs. Ambient Temperature

# Typical Performance Characteristics (Continued, f = 1.0 kHz)

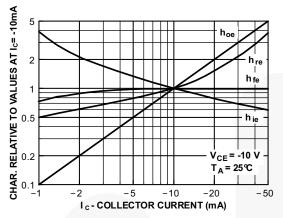


Figure 11. Common Emitter Characteristics

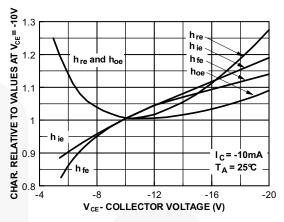


Figure 12. Common Emitter Characteristics

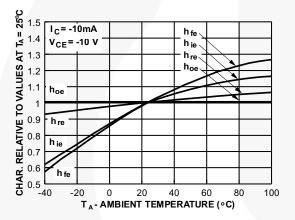


Figure 13. Common Emitter Characteristics

# **Physical Dimensions**

## SOT-23 0.95 2.92±0.20 3 1.40 1.30<sup>+0.20</sup><sub>-0.15</sub> 2.20 0.60 0.37 (0.29) -0.95 ⊕ 0.20M A B 1.00 1.90 1.90 LAND PATTERN RECOMMENDATION 1.20 MAX SEE DETAIL A (0.93)0.10 ○ 0.10 M C C 2.40±0.30 NOTES: UNLESS OTHERWISE SPECIFIED **GAGE PLANE** A) REFERENCE JEDEC REGISTRATION TO-236, VARIATION AB, ISSUE H. B) ALL DIMENSIONS ARE IN MILLIMETERS. 0.23 0.08 C) DIMENSIONS ARE INCLUSIVE OF BURRS, 0.25 MOLD FLASH AND TIE BAR EXTRUSIONS. D) DIMENSIONING AND TOLERANCING PER ASME Y14.5M - 1994. 0.20 MIN E) DRAWING FILE NAME: MA03DREV10 SEATING **PLANE** (0.55)**DETAIL A**

Figure 14. 3-LEAD, SOT23, JEDEC TO-236, LOW PROFILE (ACTIVE)

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